

**ABSTRACT OF THE DISCLOSURE**

A heat dissipating structure for an electronic device includes a heat source and a heat dissipating member. The heat dissipating member has an inner wall, 5 an outer wall, and a plurality of partition walls. The inner wall receives heat transfer from the heat source. The outer wall opposes the inner wall at a distance. The partition walls connect the inner wall and the outer wall, and together with the inner wall and outer wall define a plurality of through-holes which are approximately the same shape and are aligned at roughly regular intervals along 10 the inner wall or the outer wall. The through-holes are arranged along the vertical direction that allows most effective utilization of gravitational influence, and are open to the outside at the upper and lower ends thereof.